

## MPW schedule

Last updated: May 25, 2023

MPW name	Fab	Processes	Tape-In	Ship Date
SB*18 - B5015	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	12-06-22	06-13-23
CA18 - B5300	NPB - Fab 3	RFCMOS 0.18um (fast track)	01-24-23	07-07-23
SB*18 - B5301	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	02-07-23	08-17-23
PH18M* - B5302	NPB - Fab 3	SiPho 0.18um	02-21-23	07-07-23
PH18DA – B5304	NPB - Fab 3	SiPho 0.18um	03-21-23	09-22-23
SB*18 - B5305	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	04-04-23	10-10-23
CS18* - B5306	MH - Fab 2	CMOS-SOI 0.18um	05-02-23	
CA18 - B5307	NPB - Fab 3	RFCMOS 0.18um (fast track)	05-16-23	10-27-23
SH223T18MAY	MH - Fab 2	CIS 0.18um Image Sensor CMOS+ 0.16um, 0.18um RF, RFID, PM	05-16-23 05-23-23	
PH18M* - B5308	NPB - Fab 3	SiPho 0.18um	05-30-23	10-13-23
SB*18 - B5309	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	06-06-23	12-14-23
25th MPW - Uozu, Japan	TPSCo - Fab 7	CMOS,PM & RFCMOS, 65nm : TPS65SLA/SLC, TPS65PMA/PMB/MSA/MSB, TPS65RF	06-12-23	
25th MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	06-19-23	
SB*/CA/13* - B5310	NPB - Fab 3	SiGe BiCMOS / RF CMOS 0.13um (fast track)	06-20-23	02-16-24
SB*18- B5311	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	07-11-23	01-18-24
PH18M* - B5312	NPB - Fab 3	SiPho 0.18um	08-08-23	12-23-23
SH323T18AUG	MH - Fab 2	CIS 0.18um Image Sensor CMOS+ 0.16um, 0.18um RF, RFID, PM	08-08-23 08-15-23	
CS18* - B5313	MH - Fab 2	CMOS-SOI 0.18um	08-22-23	
26th MPW - Tonami, Japan	TPSCo - Fab 5	TS18 - CMOS 0.18u & 0.16u, PM, PM_SOI	08-28-23	
SB*18 - B5314	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	09-05-23	03-14-24
PH18DA - B5315	NPB - Fab 3	SiPho 0.18um	09-19-23	03-22-24
26th MPW - Uozu, Japan	TPSCo - Fab 7	CMOS,PM & RFCMOS, 65nm : TPS65SLA/SLC, TPS65PMA/PMB/MSA/MSB, TPS65RF	09-25-23	
SB*/CA/13* - B5316	NPB - Fab 3	SiGe BiCMOS / RF CMOS 0.13um (fast track)	10-03-23	05-31-24
27th MPW - Uozu, Japan	TPSCo - Fab 7	RFSOI, 65nm : TPS90RSB2, TPS65RSA2/RSB/RSB2	10-16-23	
CA18 - B5317	NPB - Fab 3	RFCMOS 0.18um (fast track)	10-17-23	03-29-24
PH18M* - B5318	NPB - Fab 3	SiPho 0.18um	10-31-23	03-15-24
SB*18 - B5319	NPB - Fab 3	SiGe BiCMOS 0.18um (fast track)	11-14-23	05-24-24
SH423T18NOV	MH - Fab 2	CIS 0.18um Image Sensor	11-14-23	

		CMOS+ 0.16um, 0.18um RF, RFID, PM	<b>11-21-23</b>	
<b>27th MPW - Tonami, Japan</b>	<b>TPSCo - Fab 5</b>	TS18 : CMOS 0.18u & 0.16u, PM, PM_SOI	<b>11-27-23</b>	

(fast track) = Please contact your sales representative for information on fast track processing.

Notes: "Shuttles" (SH\*) are run at Fab 2

\* 0.13u MH – fab 2 Shuttle / MPW slots will be considered per needs

Please contact your customer account manager for additional information.

Fab2 - Tower Semiconductor 200mm wafer fabrication facility at Migdal Ha'emek, Israel

Fab3 - Tower Semiconductor 200mm wafer fabrication facility at Newport Beach, CA

Fab5 - Tower Semiconductor 200mm wafer fabrication facility at Tonami, Japan

Fab7 - Tower Semiconductor 300mm wafer fabrication facility at Uozu, Japan